



Docket: CS 99-343C

S/N: 10/076,244

2813  
JRW

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

From: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No.: 10/076,244	Filed: 02/13/2002
Inventor: Yakub Aliyu	
Title: A Method of Copper/Copper Surface Bonding Using a Conducting Polymer for Application in IC Chip Bonding	
Group Art Unit: 2813	Examiner: Berezny, Nema O.
Attorney Docket: CS 99 - 343C	

### RESPONSE TO PATENT OFFICE ACTION

Dear Sir:

In response to the office action dated 03/11/2004, please consider the following remarks:

### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on June 9, 2004.

Signature/Date

6/9/04

Stephen B. Ackerman  
Reg. No. 37,761